TI Designs: CC256x Bluetooth® Reference Design

Configuration Notes:
01-EM 02-COM
RF1 Install Removed
RF2 Install Removed

REVISION HISTORY
Added C32, C36
R13 0 ohm resistor was deleted when installed connected MLDO_OUT to VBAT_CC
Delete net SLOW_CLK_DBG, connect net SLOW_CLK-EDGE to P2 pin 10.

Board Interface

Title: CC256xQFN-EM

Design Approval

Designer: CRAIG BOHREN
Drawn By: JOHN MCDOWELL

Date: Wednesday, July 10, 2013

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Bluetooth Power supply (2.2-4.8V rail + 1p8 IO supply)

VDDIO 1.8V 100mA

Power / Level Shifter

Title: CC256xQFN-EM

Size B
EDGE No 6546200
Rev 1.2B

Date: Wednesday, July 10, 2013

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CC256x HCI Class 1.5 capable Bluetooth device
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